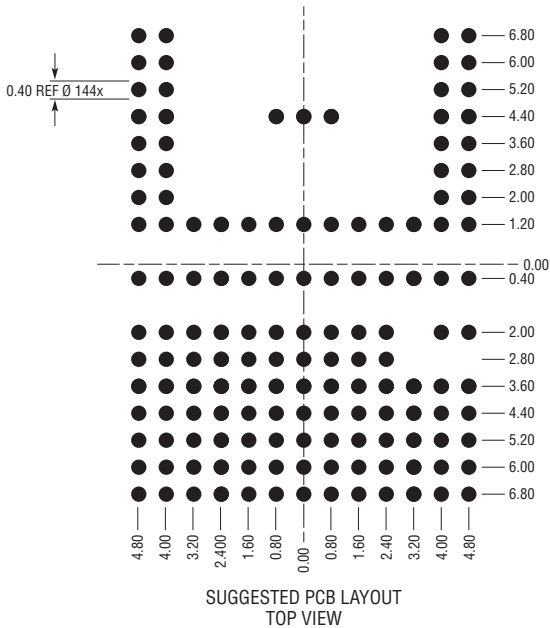
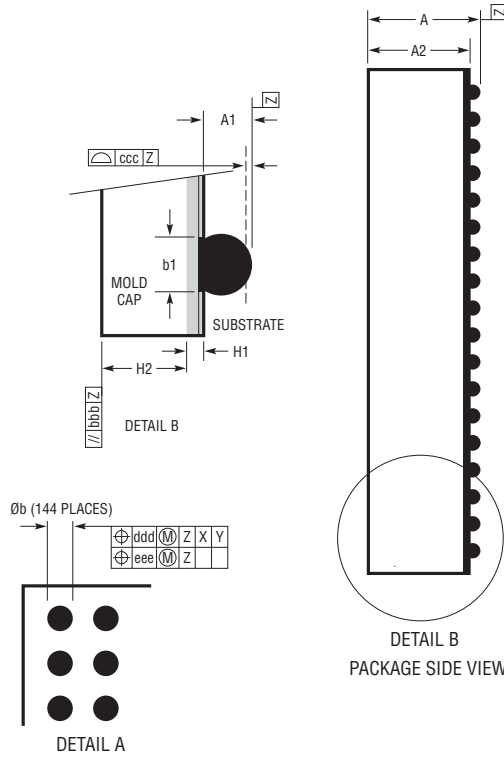
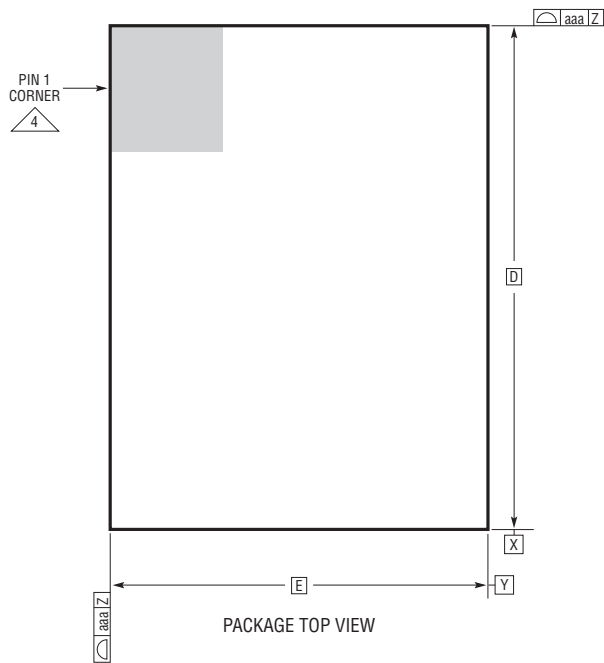
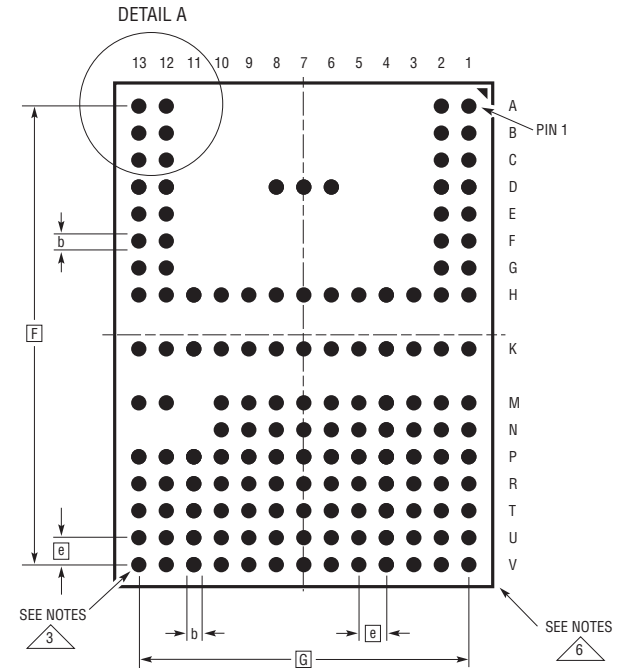


BGA Package
144-Lead (11.25mm × 15mm × 3.22mm)
 (Reference LTC DWG # 05-08-7062 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.03	3.22	3.41	
A1	0.30	0.40	0.50	BALL HT
A2	2.73	2.82	2.91	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		15.00		
E		11.25		
e		0.80		
F		13.60		
G		9.60		
H1		0.32 REF		SUBSTRATE THK
H2		2.50 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ddd			0.25	
eee			0.10	

TOTAL NUMBER OF BALLS: 144



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 - 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

